

1827341-4 ✓ ACTIVE

DDR2 SO DIMM, DDR SODIMM

TE Internal #: 1827341-4

Double Data Rate (DDR) 2, Stack Height 8 mm [.315 in], Right Angle

Module Orientation, 200 Position, DDR SODIMM, SO DIMM

Sockets

[View on TE.com >](#)



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 2**

Stack Height: **8 mm [.315 in]**

Module Orientation: **Right Angle**

Number of Positions: **200**

Centerline (Pitch): **.6 mm [.024 in]**

[All DDR2 SO DIMM Sockets \(28\)](#)

Features

Product Type Features

| | |
|-----------------------------------|--------------------------|
| DRAM Type | Double Data Rate (DDR) 2 |
| Connector & Contact Terminates To | Printed Circuit Board |
| Connector System | Cable-to-Board |

Dimensions

| | |
|--------------------|------------------|
| Stack Height | 8 mm [.315 in] |
| Row-to-Row Spacing | 6.2 mm [.244 in] |

Configuration Features

| | |
|---------------------|-------------|
| Module Orientation | Right Angle |
| Number of Positions | 200 |
| Number of Bays | 2 |
| Number of Keys | 1 |
| Number of Rows | 2 |



Housing Features

| | |
|--------------------|------------------------------|
| Centerline (Pitch) | .6 mm [.024 in] |
| Housing Material | LCP (Liquid Crystal Polymer) |
| Housing Color | Black |

Body Features

| | |
|-------------------------|-------------|
| Connector Profile | Standard |
| Retention Post Location | Center |
| Module Key Type | Offset Left |
| Ejector Type | Locking |
| Ejector Location | Both Ends |

Contact Features

| | |
|---|--------------|
| Contact Mating Area Plating Material | Gold |
| Contact Current Rating (Max) | .5 A |
| Contact Underplating Material | Nickel |
| Memory Socket Type | Memory Card |
| Contact Base Material | Copper Alloy |
| PCB Contact Termination Area Plating Material | Gold |

Packaging Features

| | |
|--------------------|-----------|
| Packaging Method | Tray, Box |
| Packaging Quantity | 20 |

Operation/Application

| | |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|

Usage Conditions

| | |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 85 °C [-67 – 185 °F] |
|-----------------------------|----------------------------|

Other

| | |
|--------------------|-----------|
| EU RoHS Compliance | Compliant |
| EU ELV Compliance | Compliant |

Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 1.8 V |
|--------------|-------|

Signal Characteristics

| | |
|---------------|-------|
| SGRAM Voltage | 1.8 V |
|---------------|-------|



Termination Features

| | |
|---------------------------|---------------|
| Insertion Style | Cam-In |
| Termination Method to PCB | Surface Mount |

Mechanical Attachment

| | |
|--------------------------|-----------------|
| Connector Mounting Type | Board Mount |
| PCB Mount Retention Type | Solder Tail |
| Mating Alignment Type | Standard Keying |
| PCB Mount Retention | With |

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

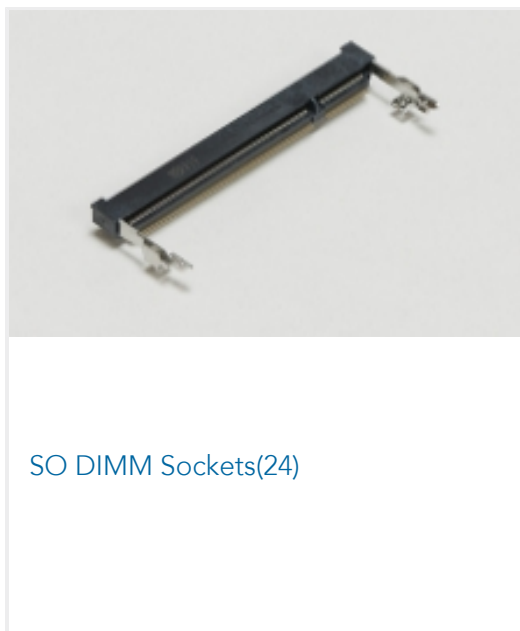
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

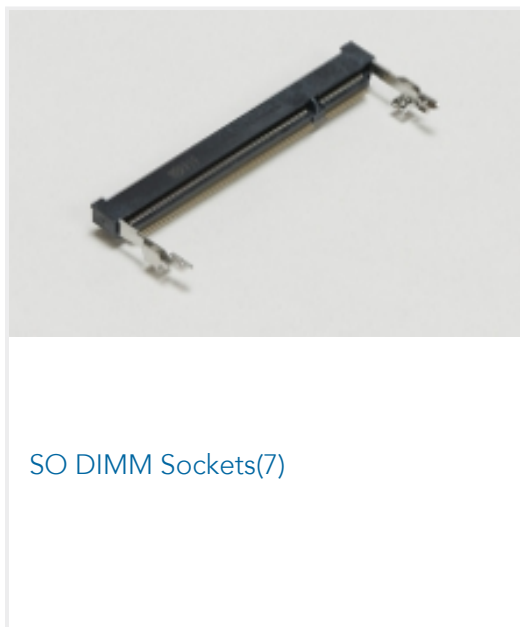
Compatible Parts



Also in the Series | [DDR2 SO DIMM](#)



Also in the Series | [DDR SODIMM](#)



Customers Also Bought

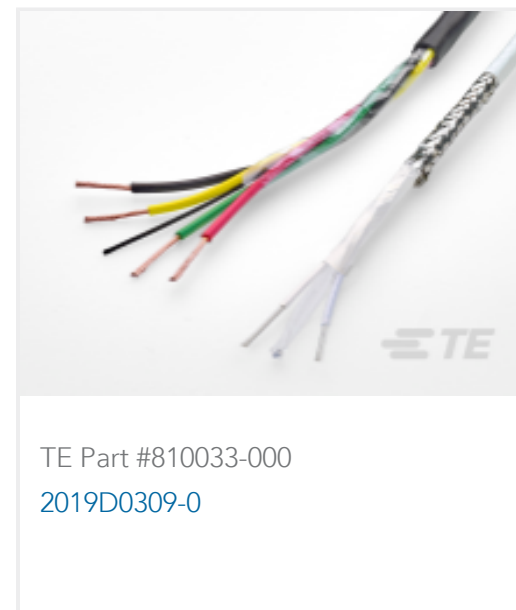




TE Part #4-640440-8
18P MTA100 CONN ASSY 22AWG RED



TE Part #796642-5
SPOS 5.0MM CE VRT HDR,TRM BLK



TE Part #810033-000
2019D0309-0



TE Part #354175-E
MSPEED 50 F SMDTHR F4 B AB VV
137 094 *



TE Part #374722-E
MSPEED 50 M SMDTHR * 90BE AB VV
137 094

Documents

Product Drawings

DDR SODIMM SOCKET 200P 8H STD TYPE

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1827341-4_G1.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1827341-4_G1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1827341-4_G1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Product Specification

English